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Product Change Notification - CYER-110SAZ739

25 Jun 2010 Date:

Product Category: Analog (Linear & Mixed Signal) AND Interface; Analog (Thermal, Power Management & Safety)

Device Family:

Notification subject: CCB 947: Qualification of larger paddle in 8L MSOP package with G600F mold compound at MMS (ATES) assembly site.

Notification text: PCN Status:

Final notification

Microchip Part#s Affected:

See attachments of Affected Part Numbers Labeled as...

PCN_CYER-11OSAZ739_CPN_Affected.xls PCN_CYER-11OSAZ739_CPN_Affected.pdf

Description of Change:

Qualification of larger paddle in 8L MSOP package with G600F mold compound at MMS (ATES) assembly site.

Mold compound: MP8000CH4. Paddle size: 68 x 94 mils paddle

Post Change:

Mold Compound: G600F. Paddle size: 71 x 96 mils paddle

Impacts to Data Sheet:

None

Reason for Change:

To improve manufacturability

Change Implementation Status:

In Progress

Estimated First Ship Date: July 30, 2010 (Date code 1031)

NOTE: Please be advised that during the transition period customers may receive pre and post change parts,

due to existing inventory of the pre changed parts.

Markings to Distinguish Revised from Unrevised Devices: (e.g.: Date Code, Device Marking, Ship Container

Marking)

Traceability code

PCN_CYER-11OSAZ739 Affected_CPN.xis PCN_CYER-11OSAZ739 CPN_Affected.pdf PCN_CYER-11OSAZ739 Qual Report.pdf Attachment(s):

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CYER-11OSAZ739 - CCB 947: Qualification of larger paddle in 8L MSOP package with G600F mold compound at MMS (ATES) assembly site. Parts Affected MCP6282 MCP6292 TC1301A TC1301B MCP1253 MCP9801 TC1029 TC1300 **TC72** MCP1252-33X50 MCP1252-ADJ MCP1253-33X50 MCP1253-ADJ MCP1601 MCP1650 MCP1651 MCP1652 MCP3001 MCP3002 MCP3201 MCP3202 MCP3301 MCP6002 MCP6042 MCP6141 MCP6142 MCP616 MCP617 MCP618 MCP6231 MCP6232 MCP6241 MCP6242 MCP6273 MCP6275 MCP6285 MCP6293 MCP6295 MCP6541 MCP6542 MCP6543 MCP6546 MCP6547

Date: Monday, August 23, 2010

CYER-11OSAZ739 - CCB 947: Qualification of larger paddle in 8L MSOP package with G600F mold compound at MMS (ATES) assembly site. MCP6548 MCP6L02 MCP6L2 MCP6L92 MCP6S91 MCP6S92 MCP73828 MCP73843 MCP73844 TC1026 TC1041 TC1107 TC1121 TC1173 TC1174 TC1266 TC1302A TC1302B TC1320 TC1321 TC1410 TC1410N TC1411 TC1411N TC4426A TC4427A TC4428A TC642B TC646B TC647B TC648B TC649B TC650 TC651 TC652 TC653 TCN75